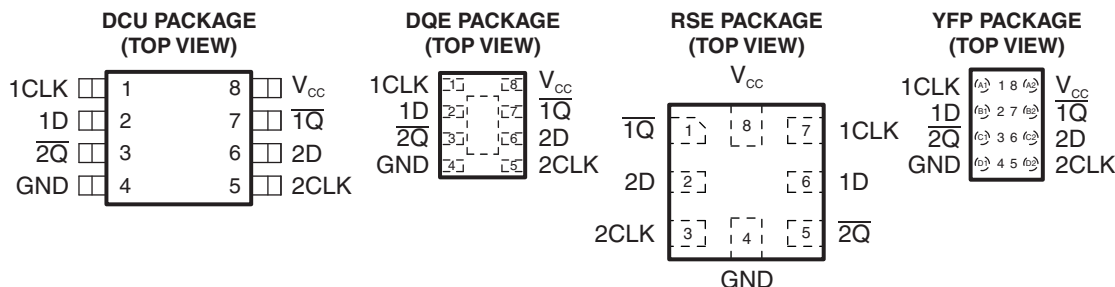


LOW-POWER DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP

Check for Samples: [SN74AUP2G80](#)

FEATURES

- Available in the Texas Instruments NanoStar™ Package
- Low Static-Power Consumption ($I_{CC} = 0.9 \mu A$ Maximum)
- Low Dynamic-Power Consumption ($C_{pd} = 4.3 pF$ Typ at 3.3 V)
- Low Input Capacitance ($C_i = 1.5 pF$ Typical)
- Low Noise – Overshoot and Undershoot <10% of V_{CC}
- I_{off} Supports Partial-Power-Down Mode Operation
- Wide Operating V_{CC} Range of 0.8 V to 3.6 V
- Optimized for 3.3-V Operation
- 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- $t_{pd} = 4.4 ns$ Maximum at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static- and dynamic-power consumption across the entire V_{CC} range of 0.8 V to 3.6 V, resulting in increased battery life (see [Figure 1](#)). This product also maintains excellent signal integrity (see the very low undershoot and overshoot characteristics shown in [Figure 2](#)).

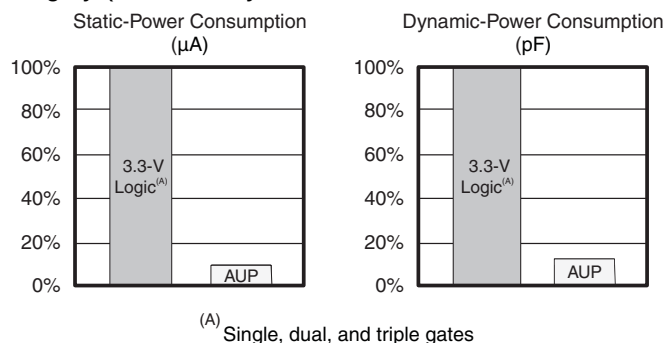
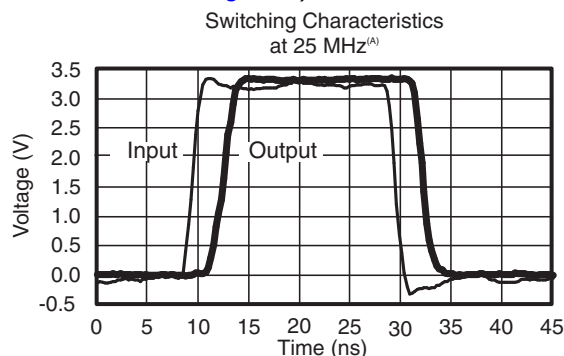

Figure 1. AUP – The Lowest-Power Family

(A) SN74AUP2Gxx data at $C_L = 15 pF$.

Figure 2. Excellent Signal Integrity


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

When data at the data (D) input meets the setup time requirement, the data is transferred to the Q output on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

NanoStar™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION⁽¹⁾

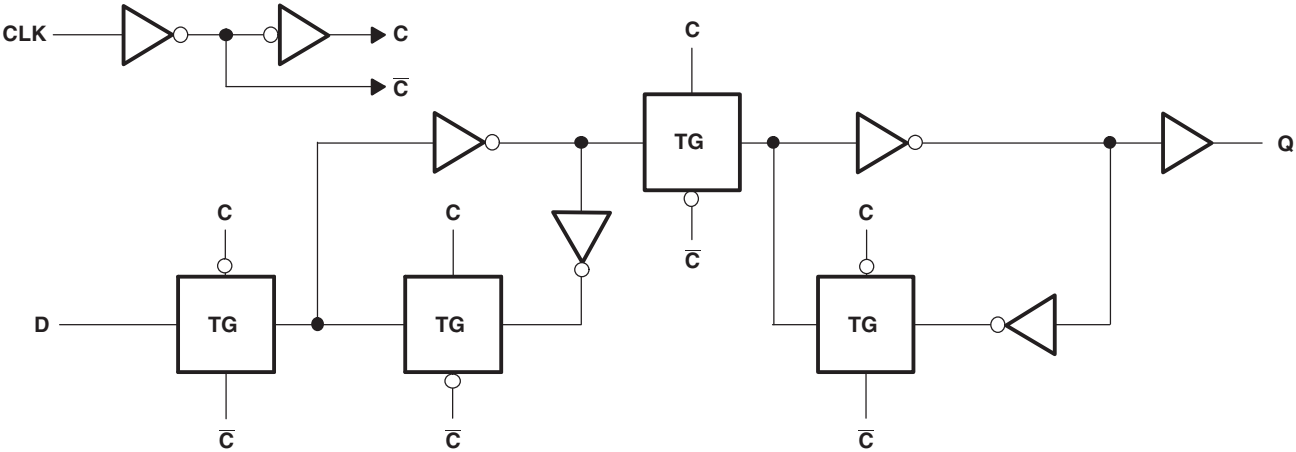
T_A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽³⁾
–40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YFP (Pb-free)	Reel of 3000	SN74AUP2G80YFPR	___ H X _
	uQFN – DQE	Reel of 5000	SN74AUP2G80DQER	PU
	QFN – RSE	Reel of 5000	SN74AUP2G80RSE	PU
	SSOP – DCU	Reel of 3000	SN74AUP2G80DCUR	H80_

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (3) DCU: The actual top-side marking has one additional character that designates the wafer fab/assembly site.
YFP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the wafer fab/assembly site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

FUNCTION TABLE

INPUTS		OUTPUT Q
CLK	D	
↑	H	L
↑	L	H
L	X	Q_0

LOGIC DIAGRAM (POSITIVE LOGIC)



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		–0.5	4.6	V
V _I	Input voltage range ⁽²⁾		–0.5	4.6	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾		–0.5	4.6	V
V _O	Output voltage range in the high or low state ⁽²⁾		–0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		–50	mA
I _{OK}	Output clamp current	V _O < 0		–50	mA
I _O	Continuous output current			±20	mA
	Continuous current through V _{CC} or GND			±50	mA
θ _{JA}	Package thermal impedance ⁽³⁾	DCU package		220	°C/W
		DQE package		261	
		RSE package		253	
		YFP package		132	
T _{stg}	Storage temperature range		–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

RECOMMENDED OPERATING CONDITIONS			MIN	MAX	UNIT
V _{CC}	Supply voltage		0.8	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 0.8 V	V _{CC}		V
		V _{CC} = 1.1 V to 1.95 V	0.65 × V _{CC}		
		V _{CC} = 2.3 V to 2.7 V	1.6		
		V _{CC} = 3 V to 3.6 V	2		
V _{IL}	Low-level input voltage	V _{CC} = 0.8 V	0		V
		V _{CC} = 1.1 V to 1.95 V	0.35 × V _{CC}		
		V _{CC} = 2.3 V to 2.7 V	0.7		
		V _{CC} = 3 V to 3.6 V	0.9		
V _I	Input voltage		0	3.6	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 0.8 V	−20		μA
		V _{CC} = 1.1 V	−1.1		mA
		V _{CC} = 1.4 V	−1.7		
		V _{CC} = 1.65	−1.9		
		V _{CC} = 2.3 V	−3.1		
		V _{CC} = 3 V	−4		
I _{OL}	Low-level output current	V _{CC} = 0.8 V	20		μA
		V _{CC} = 1.1 V	1.1		mA
		V _{CC} = 1.4 V	1.7		
		V _{CC} = 1.65 V	1.9		
		V _{CC} = 2.3 V	3.1		
		V _{CC} = 3 V	4		
Δt/Δv	Input transition rise or fall rate	V _{CC} = 0.8 V to 3.6 V	200		ns/V
T _A	Operating free-air temperature		−40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = −40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
V _{OH}		I _{OH} = −20 μA	0.8 V to 3.6 V	V _{CC} − 0.1			V _{CC} − 0.1		V
		I _{OH} = −1.1 mA	1.1 V	0.75 × V _{CC}			0.7 × V _{CC}		
		I _{OH} = −1.7 mA	1.4 V	1.11			1.03		
		I _{OH} = −1.9 mA	1.65 V	1.32			1.3		
		I _{OH} = −2.3 mA	2.3 V	2.05			1.97		
		I _{OH} = −3.1 mA		1.9			1.85		
		I _{OH} = −2.7 mA	3 V	2.72			2.67		
		I _{OH} = −4 mA		2.6			2.55		
V _{OL}		I _{OL} = 20 μA	0.8 V to 3.6 V	0.1			0.1		V
		I _{OL} = 1.1 mA	1.1 V	0.3 × V _{CC}			0.3 × V _{CC}		
		I _{OL} = 1.7 mA	1.4 V	0.31			0.37		
		I _{OL} = 1.9 mA	1.65 V	0.31			0.35		
		I _{OL} = 2.3 mA	2.3 V	0.31			0.33		
		I _{OL} = 3.1 mA		0.44			0.45		
		I _{OL} = 2.7 mA	3 V	0.31			0.33		
		I _{OL} = 4 mA		0.44			0.45		
I _I	A or B input	V _I = GND to 3.6 V	0 V to 3.6 V	0.1			0.5	μA	
I _{off}		V _I or V _O = 0 V to 3.6 V	0 V	0.2			0.6	μA	
ΔI _{off}		V _I or V _O = 0 V to 3.6 V	0 V to 0.2 V	0.2			0.6	μA	
I _{CC}		V _I = GND or (V _{CC} to 3.6 V), I _O = 0	0.8 V to 3.6 V	0.5			0.9	μA	
ΔI _{CC}		V _I = V _{CC} − 0.6 V ⁽¹⁾ , I _O = 0	3.3 V	40			50	μA	
C _i		V _I = V _{CC} or GND	0 V	1.5					pF
			3.6 V	1.5					
C _o		V _O = GND	0 V	3					pF

(1) One input at $V_{CC} - 0.6\ \text{V}$, other input at V_{CC} or GND

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#))

		V_{CC}	$T_A = 25^\circ\text{C}$	$T_A = -40^\circ\text{C}$ to 85°C		UNIT
			TYP	MIN	MAX	
f_{clock}	Clock frequency	0.8 V			20	MHz
		1.2 V $\pm$ 0.1 V			80	
		1.5 V $\pm$ 0.1 V			120	
		1.8 V $\pm$ 0.15 V			160	
		2.5 V $\pm$ 0.2 V			220	
		3.3 V $\pm$ 0.3 V			260	
t_w	Pulse duration, CLK high or low	0.8 V		5.5		
		1.2 V $\pm$ 0.1 V		2.5		
		1.5 V $\pm$ 0.1 V		1.5		
		1.8 V $\pm$ 0.15 V		1.6		
		2.5 V $\pm$ 0.2 V		1.7		
		3.3 V $\pm$ 0.3 V		1.9		
t_{su}	Setup time before CLK $\uparrow$	0.8 V	3.4	6.7		ns
		1.2 V $\pm$ 0.1 V		2.4		
		1.5 V $\pm$ 0.1 V		1.2		
		1.8 V $\pm$ 0.15 V		0.8		
		2.5 V $\pm$ 0.2 V		0.6		
		3.3 V $\pm$ 0.3 V		0.4		
	Data low	0.8 V	3.4	8.9		ns
		1.2 V $\pm$ 0.1 V		2		
		1.5 V $\pm$ 0.1 V		1.3		
		1.8 V $\pm$ 0.15 V		1.1		
		2.5 V $\pm$ 0.2 V		0.8		
		3.3 V $\pm$ 0.3 V		0.7		
t_h	Hold time, data after CLK $\uparrow$	0.8 V	0	1		ns
		1.2 V $\pm$ 0.1 V		0		
		1.5 V $\pm$ 0.1 V		0		
		1.8 V $\pm$ 0.15 V		0		
		2.5 V $\pm$ 0.2 V		0		
		3.3 V $\pm$ 0.3 V		0		

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $C_L = 5$ pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
$f_{\max}$			0.8 V		91		90		MHz
			1.2 V $\pm$ 0.1 V		175		220		
			1.5 V $\pm$ 0.1 V		237		230		
			1.8 V $\pm$ 0.15 V		269		240		
			2.5 V $\pm$ 0.2 V		280		250		
			3.3 V $\pm$ 0.3 V		280		260		
t_{pd}	CLK	$\bar{Q}$	0.8 V		17.2				ns
			1.2 V $\pm$ 0.1 V	3.2	7.1	14.9	2.7	16.3	
			1.5 V $\pm$ 0.1 V	1.9	5	9.8	2.1	10.3	
			1.8 V $\pm$ 0.15 V	1.7	3.9	7.6	1.6	8.1	
			2.5 V $\pm$ 0.2 V	1.4	2.8	5.3	1.2	5.6	
			3.3 V $\pm$ 0.3 V	1.2	2.2	4.1	1	4.4	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $C_L = 10$ pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
$f_{\max}$			0.8 V		68		70		MHz
			1.2 V $\pm$ 0.1 V		128		170		
			1.5 V $\pm$ 0.1 V		189		220		
			1.8 V $\pm$ 0.15 V		234		240		
			2.5 V $\pm$ 0.2 V		273		250		
			3.3 V $\pm$ 0.3 V		280		260		
t_{pd}	CLK	$\bar{Q}$	0.8 V		19.4				ns
			1.2 V $\pm$ 0.1 V	4.4	8.2	16.2	3.4	17.7	
			1.5 V $\pm$ 0.1 V	3.6	5.8	10.7	2.6	11.3	
			1.8 V $\pm$ 0.15 V	2.9	4.6	8.4	2.1	3	
			2.5 V $\pm$ 0.2 V	2.2	3.3	5.9	1.7	6.3	
			3.3 V $\pm$ 0.3 V	1.9	2.7	4.7	1.4	4.9	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $C_L = 15$ pF (unless otherwise noted) (see Figure 3 and Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
$f_{\max}$			0.8 V		52		50		MHz
			1.2 V $\pm$ 0.1 V		98		130		
			1.5 V $\pm$ 0.1 V		148		180		
			1.8 V $\pm$ 0.15 V		196		240		
			2.5 V $\pm$ 0.2 V		249		250		
			3.3 V $\pm$ 0.3 V		280		260		
t_{pd}	CLK	$\bar{Q}$	0.8 V		21.5				ns
			1.2 V $\pm$ 0.1 V	3	9.1	17.4	4.1	19	
			1.5 V $\pm$ 0.1 V	3.2	6.5	11.7	3.2	12.3	
			1.8 V $\pm$ 0.15 V	2.7	4.2	9.2	2.6	9.8	
			2.5 V $\pm$ 0.2 V	2.2	3.8	6.5	2.1	6.9	
			3.3 V $\pm$ 0.3 V	1.9	3.1	5.1	1.8	5.5	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $C_L = 30$ pF (unless otherwise noted) (see Figure 3 and Figure 4)

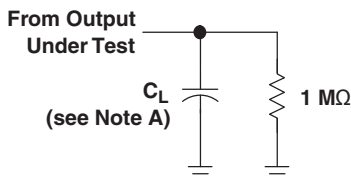
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
$f_{\max}$			0.8 V		32		20		MHz
			1.2 V $\pm$ 0.1 V		71		80		
			1.5 V $\pm$ 0.1 V		104		120		
			1.8 V $\pm$ 0.15 V		133		160		
			2.5 V $\pm$ 0.2 V		181		220		
			3.3 V $\pm$ 0.3 V		257		260		
t_{pd}	CLK	$\bar{Q}$	0.8 V		28.4				ns
			1.2 V $\pm$ 0.1 V	5.1	11.8	20.7	6.2	28.7	
			1.5 V $\pm$ 0.1 V	4.8	8.5	14.1	6.9	16.7	
			1.8 V $\pm$ 0.15 V	4	6.9	11.2	2	13.3	
			2.5 V $\pm$ 0.2 V	3.3	5.1	7.9	3.2	9.3	
			3.3 V $\pm$ 0.3 V	2.9	4.2	6.4	2.8	7.5	

OPERATING CHARACTERISTICS

$T_A = 25^\circ\text{C}$

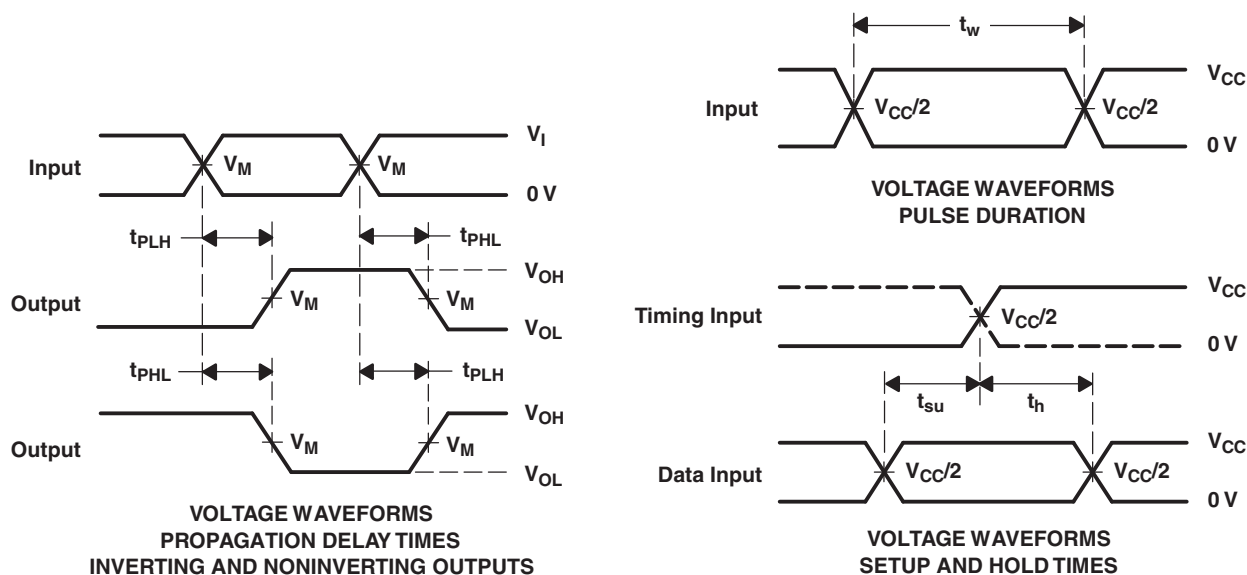
PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$f = 10$ MHz	0.8 V	4	pF
			1.2 V $\pm$ 0.1 V	4	
			1.5 V $\pm$ 0.1 V	4	
			1.8 V $\pm$ 0.15 V	4	
			2.5 V $\pm$ 0.2 V	4.1	
			3.3 V $\pm$ 0.3 V	4.3	

PARAMETER MEASUREMENT INFORMATION (Propagation Delays, Setup and Hold Times, and Pulse Width)



LOAD CIRCUIT

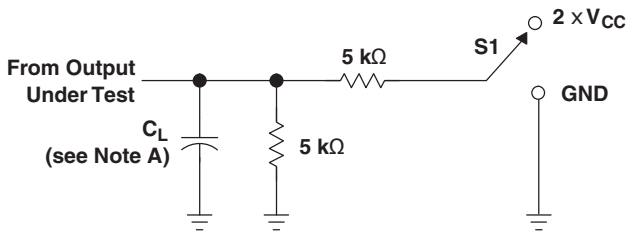
	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V}$ $\pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V}$ $\pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



- C_L includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, for propagation delays $t_r/t_f = 3 \text{ ns}$, for setup and hold times and pulse width $t_r/t_f = 1.2 \text{ ns}$.
- The outputs are measured one at a time, with one transition per measurement.
- t_{PLH} and t_{PHL} are the same as t_{pd} .
- All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

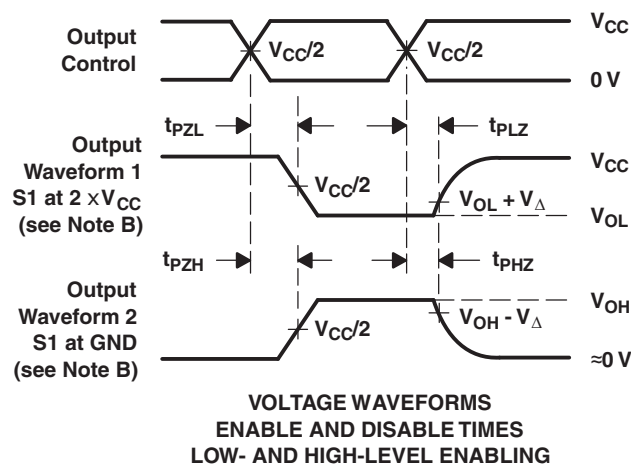
PARAMETER MEASUREMENT INFORMATION (Enable and Disable Times)



LOAD CIRCUIT

TEST	S1
t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	2 $\times V_{CC}$ GND

	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V}$ $\pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V}$ $\pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_{Δ}	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r/t_f = 3 \text{ ns}$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PLH} and t_{PHL} are the same as t_{pd} .
- G. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AUP2G80DCUR	ACTIVE	VSSOP	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	H80R	Samples
SN74AUP2G80DQER	ACTIVE	X2SON	DQE	8	5000	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	PU	Samples
SN74AUP2G80RSER	ACTIVE	UQFN	RSE	8	5000	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	PU	Samples
SN74AUP2G80YFPR	ACTIVE	DSBGA	YFP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	HXN	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

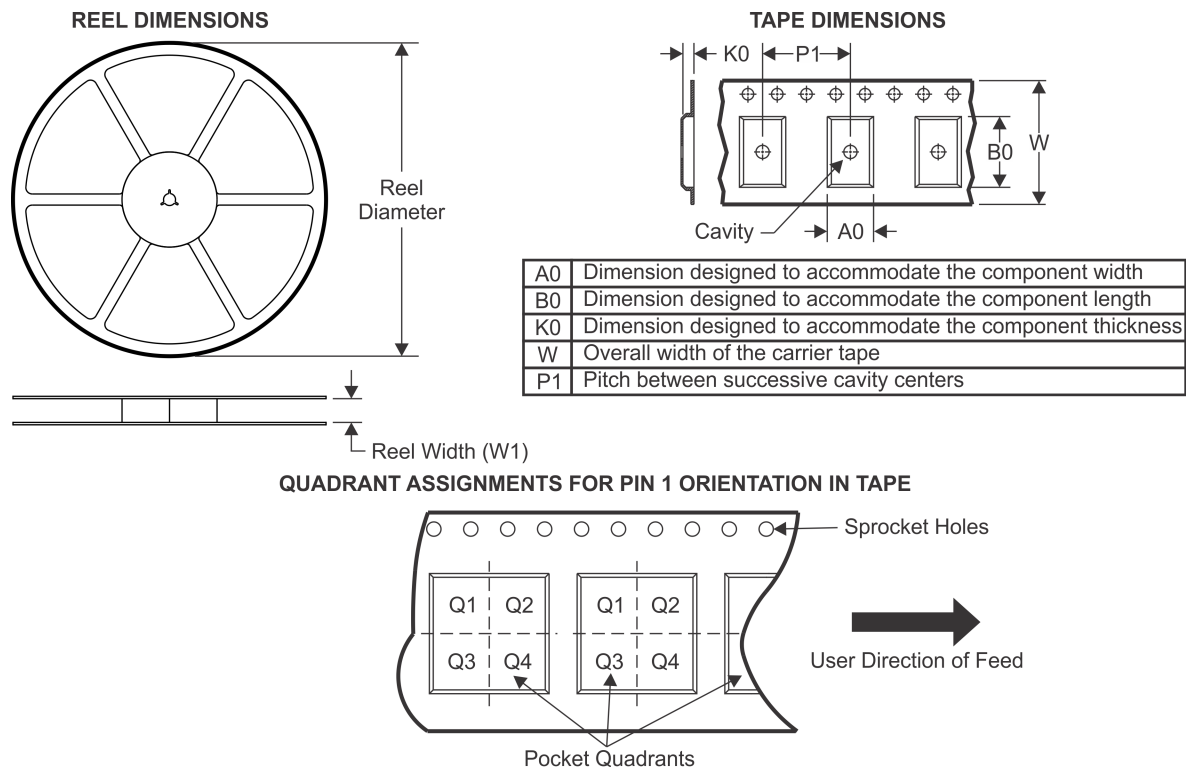
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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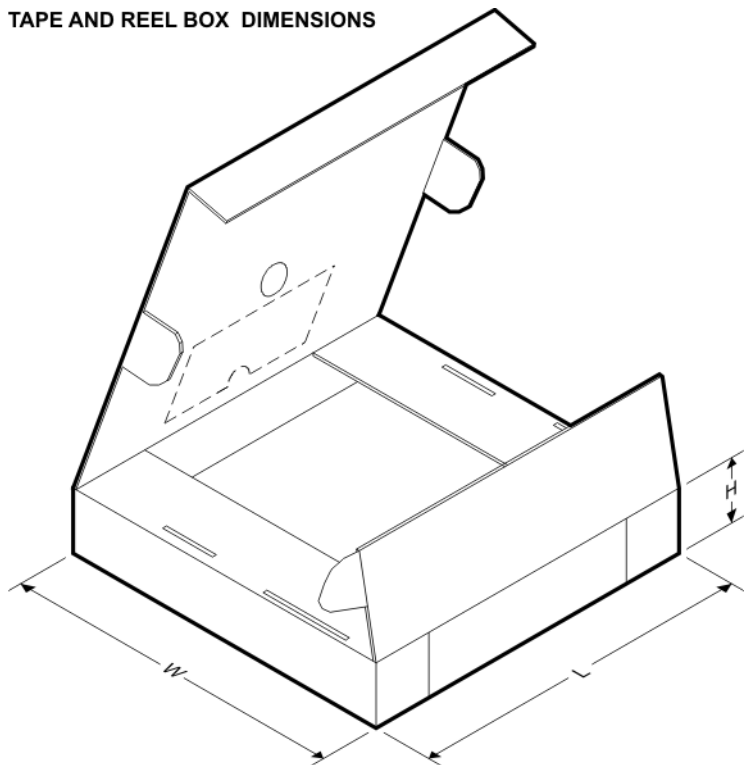
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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP2G80DCUR	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74AUP2G80DQER	X2SON	DQE	8	5000	180.0	8.4	1.2	1.6	0.55	4.0	8.0	Q1
SN74AUP2G80RSER	UQFN	RSE	8	5000	180.0	8.4	1.7	1.7	0.7	4.0	8.0	Q2
SN74AUP2G80YFPR	DSBGA	YFP	8	3000	178.0	9.2	0.9	1.75	0.6	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

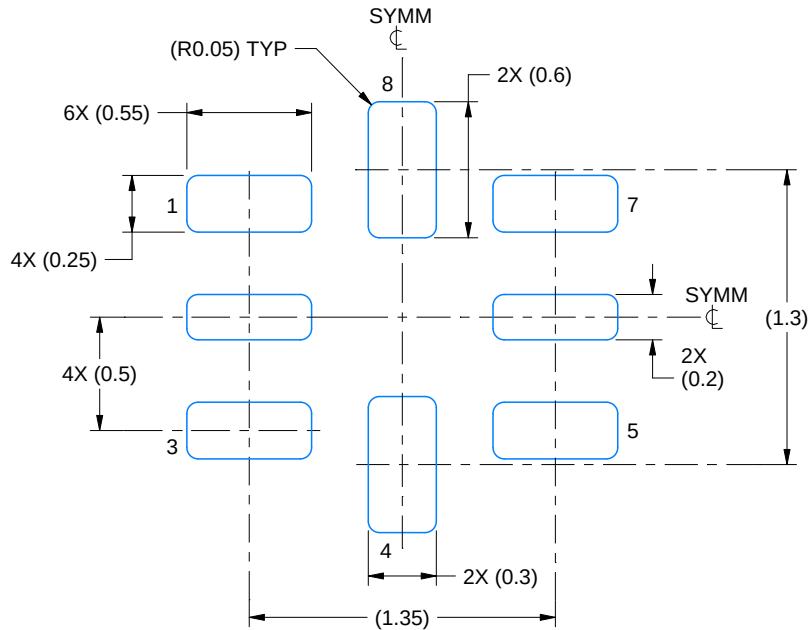
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP2G80DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
SN74AUP2G80DQER	X2SON	DQE	8	5000	202.0	201.0	28.0
SN74AUP2G80RSER	UQFN	RSE	8	5000	202.0	201.0	28.0
SN74AUP2G80YFPR	DSBGA	YFP	8	3000	220.0	220.0	35.0

EXAMPLE BOARD LAYOUT

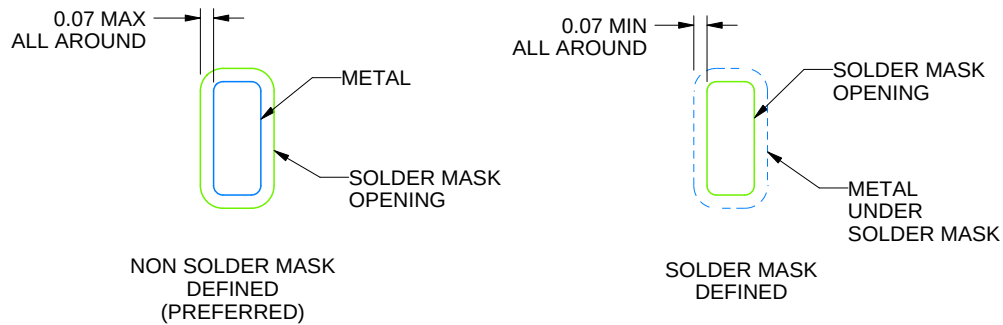
RSE0008A

UQFN - 0.6 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
SCALE:30X



SOLDER MASK DETAILS
NOT TO SCALE

4220323/B 03/2018

NOTES: (continued)

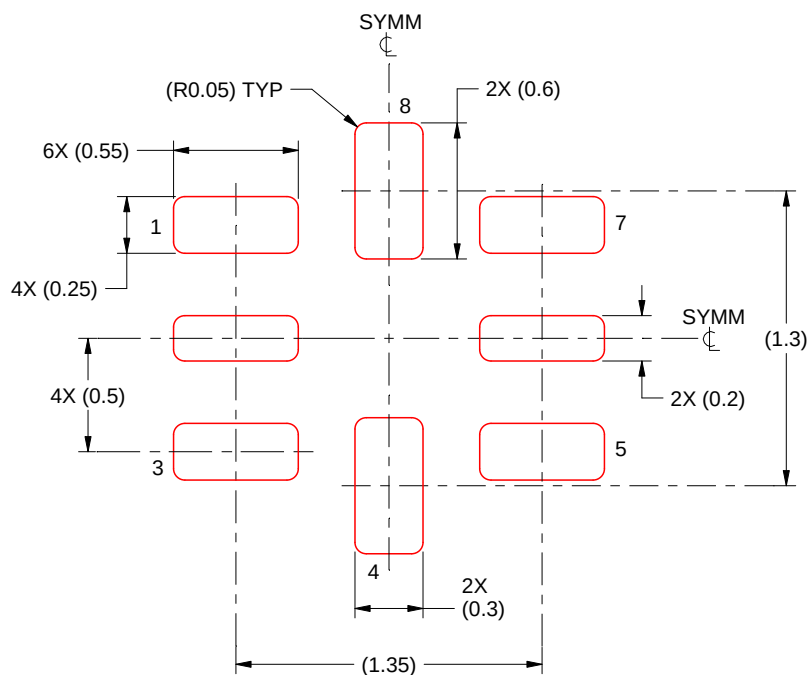
3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

RSE0008A

UQFN - 0.6 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICKNESS
SCALE: 30X

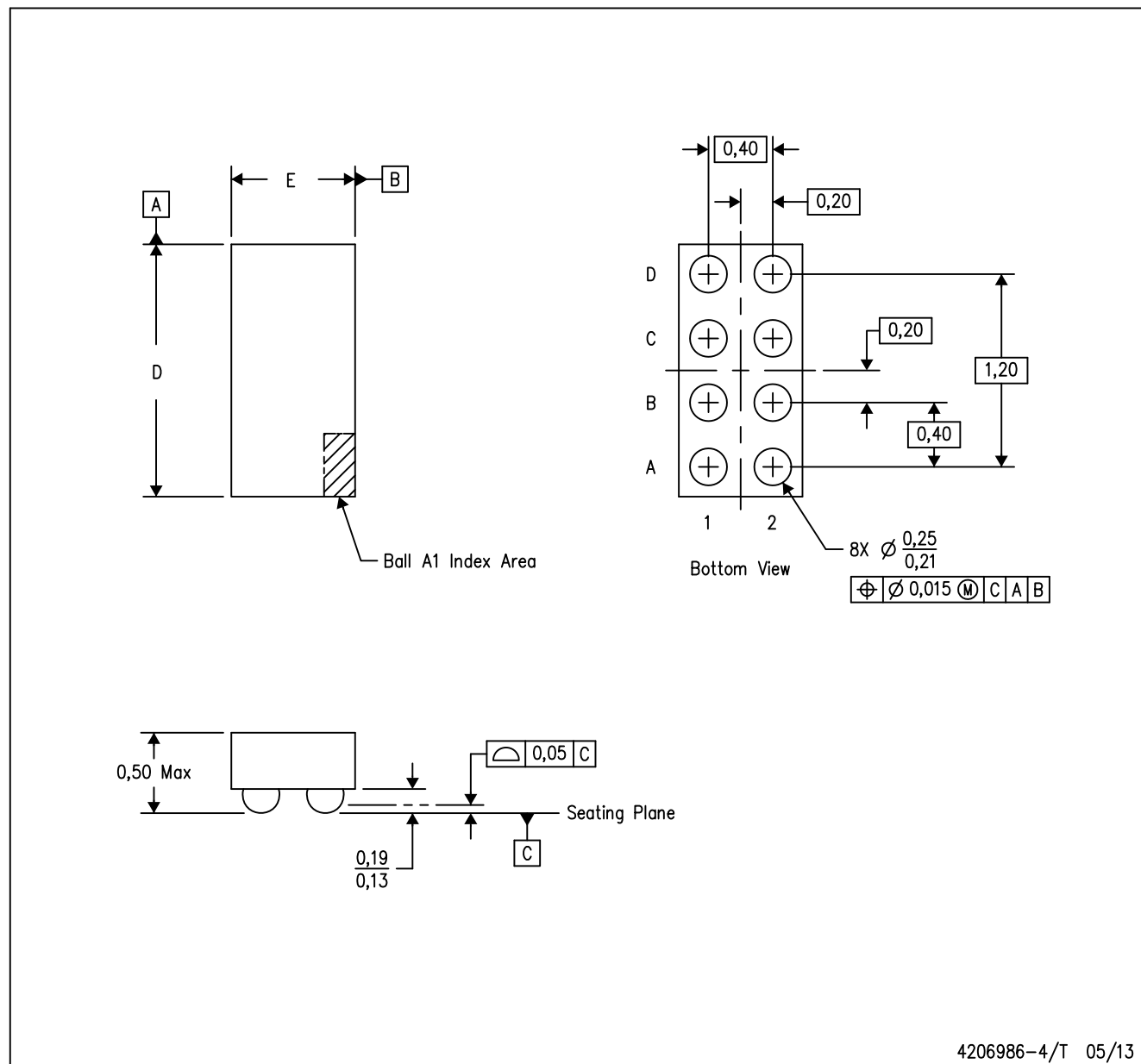
4220323/B 03/2018

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

YFP (R-XBGA-N8)

DIE-SIZE BALL GRID ARRAY

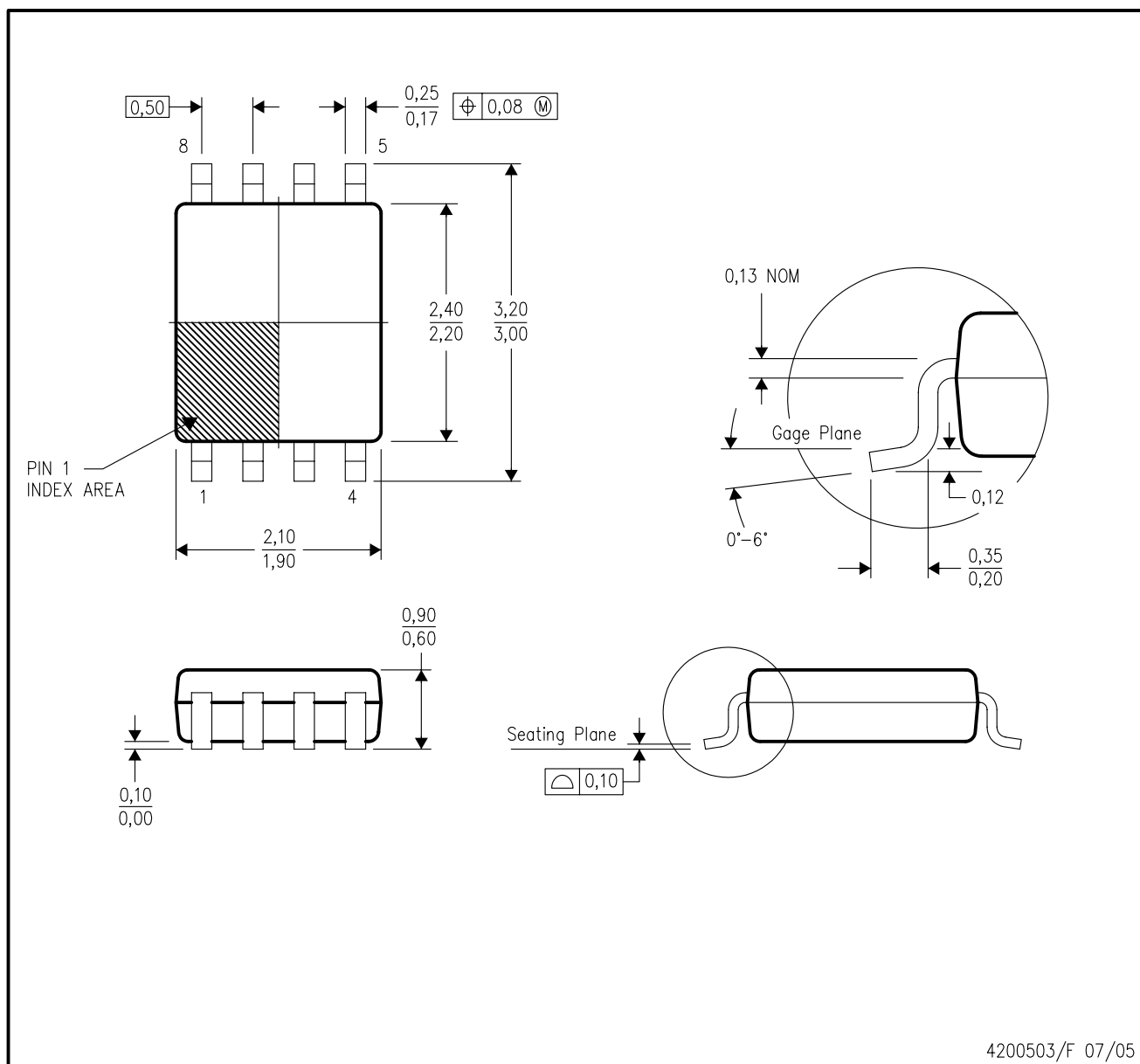


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.

NanoFree is a trademark of Texas Instruments

DCU (R-PDSO-G8)

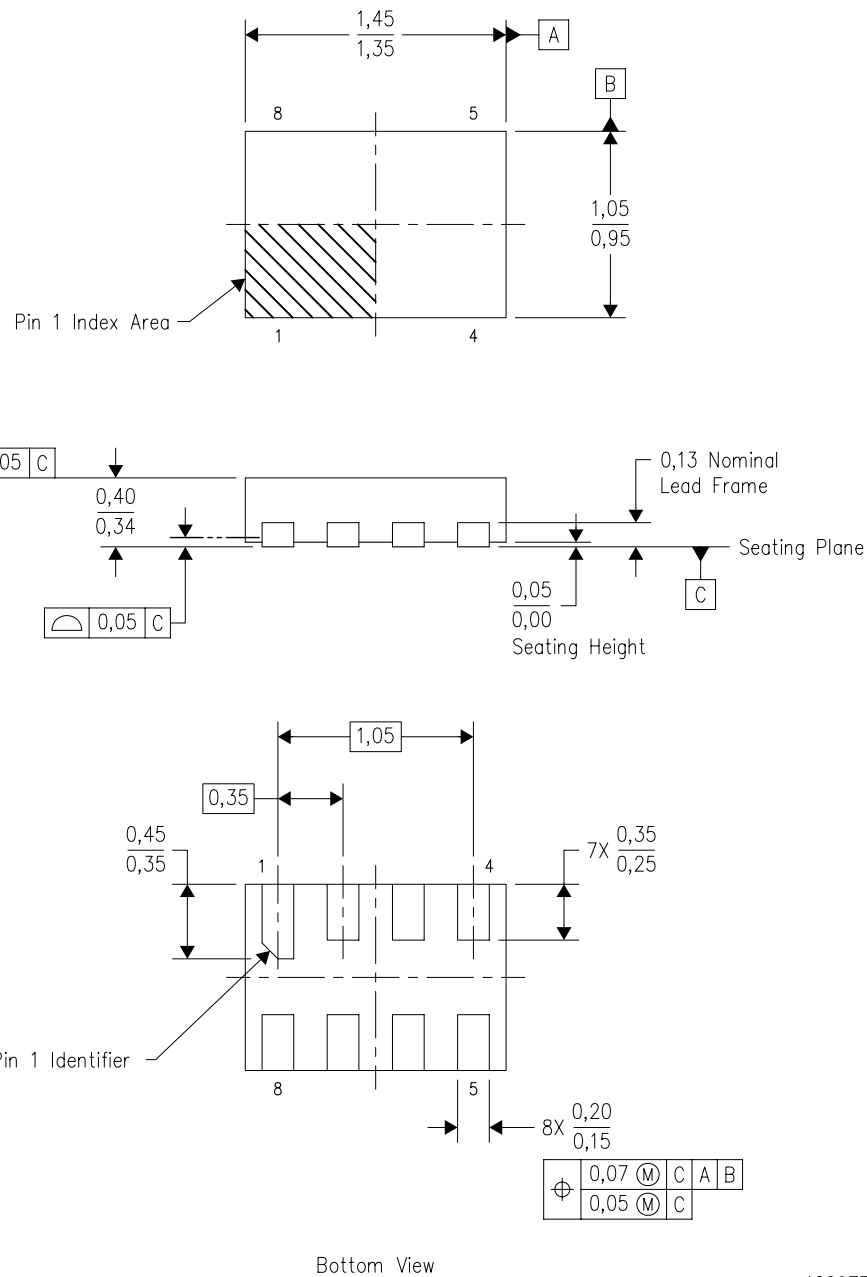
PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - Falls within JEDEC MO-187 variation CA.

DQE (R-PX2SON-N8)

PLASTIC SMALL OUTLINE NO-LEAD

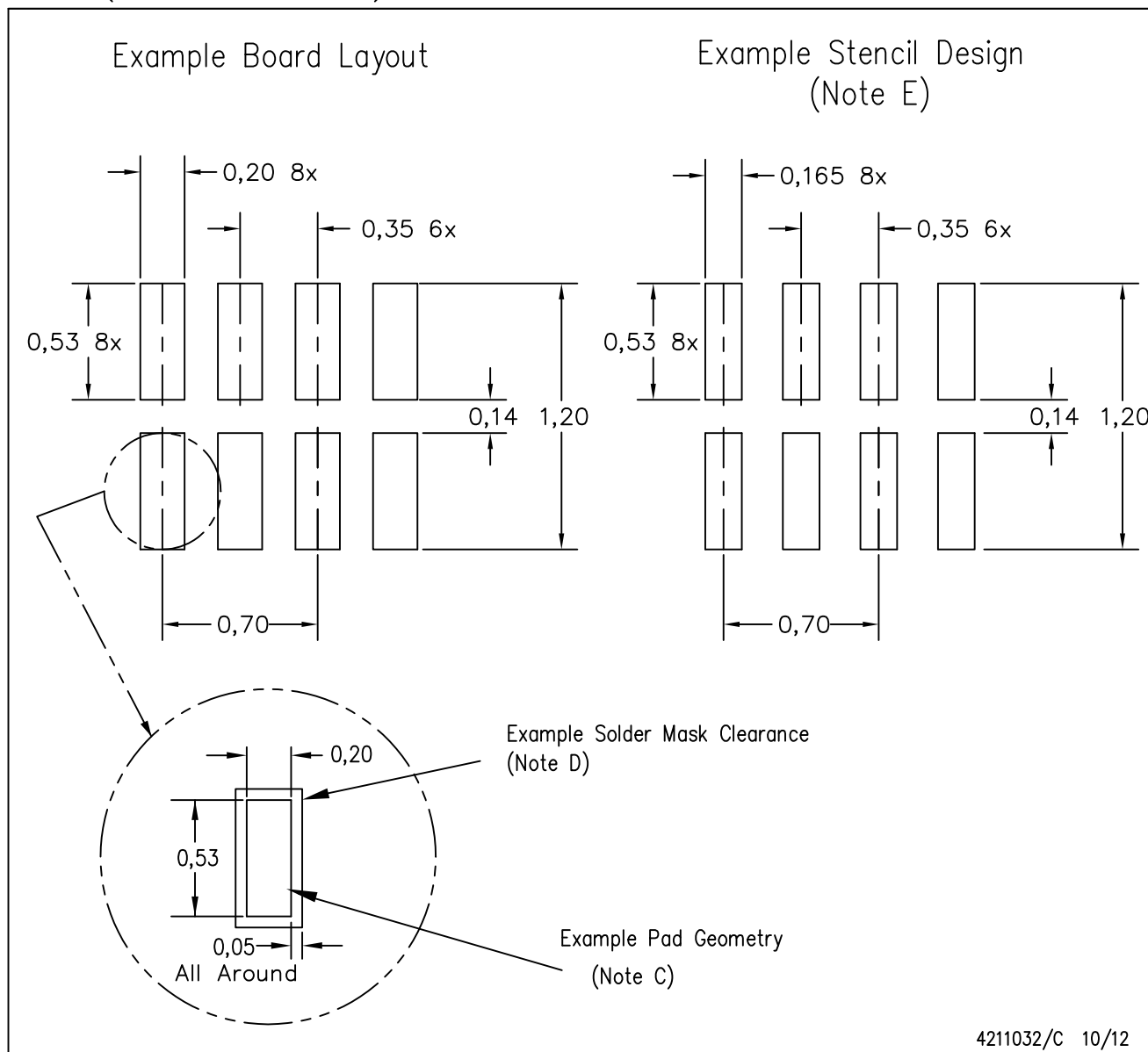


4209779/B 10/2008

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - SON (Small Outline No-Lead) package configuration.
 - This package complies to JEDEC MO-287 variation X2EAF.

DQE (R-PX2SON-N8)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
If 2 mil solder mask is outside PCB vendor capability, it is advised to omit solder mask.
 - E. Maximum stencil thickness 0,1016 mm (4 mils). All linear dimensions are in millimeters.
 - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - G. Over-printing land for acceptable area ratio is not viable due to land width and bridging potential. Customer may further reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.
 - H. Suggest stencils cut with lasers such as Fiber Laser that produce the greatest positional accuracy.
 - I. Component placement force should be minimized to prevent excessive paste block deformation.

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